



	TE	CHNICAL DATA SH	IEET	2/8
RIGHT A	NGLE H2.6 REG	Г ТҮРЕ	R107.103.020	
	REEL		Series : UMP	
PACKAGINGStandardUnitOther700-Contact us			SPECIFICATION	
ELECTRICAL CHARACTERISTICS			ENVIRONMENTAL	
Impedance Frequency VSWR Insertion loss RF leakage Voltage rating	0 1.05 + 0.03 - ( N	50 Ω -6 GHz 30 x F(GHz) Maxi (A $\sqrt{F(GHz)}$ dB Maxi (A - F(GHz)) dB Maxi 00 Veff Maxi	Operating temperature -40/+125 ° C Hermetic seal NA Atm.cm3/s Panel leakage NA	
Dielectric withstanding voltage350Veff miniInsulation resistance1000MΩ mini		OTHERS CHARACTERISTICS		
			Assembly instruction Others :	ction NA
MECHAN	ICAL CHARACT	ERISTICS		
Center contact retent Axial force – Matin Axial force – Oppos Torque	g end	<ul><li>N mini</li><li>N mini</li><li>N.cm mini</li></ul>		
Recommended torqu Mating Panel nut	e	- N.cm - N.cm		
Mating life Weight		00 Cycles mini 49 g		
<b>Issue :</b> 0417 B In the effort to improve necessary.	e our products, we rese	rve the right to make ch	anges judged to be	RADIALL®

#### TECHNICAL DATA SHEET

#### **RIGHT ANGLE H2.6 RECEPTACLE SMT TYPE**

**REEL 700** 

**R107.103.020** 

Series : UMP

## SOLDER PROCEDURE OF UMP RECEPTACLE IN INDUSTRIAL ENVIRONMENT

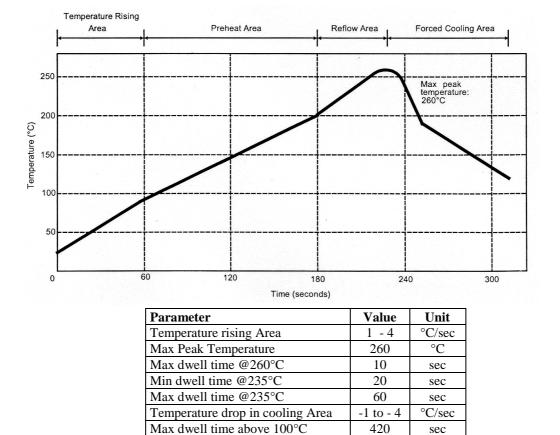
- Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.

A video camera is recommended for positioning of the component.

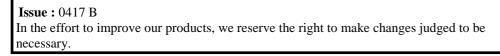
Adhesive agents must not be used on the receptacle.

- 3. This process of soldering has been tested with convection oven. Below please find, the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged.
- 5. Verification of solder joints and position of the component by visual inspection.

## NOTE : THE UMP RECEPTACLE AND THE UMP PLUG MUST NOT BE MATED BEFORE COMPLETION OF THIS PROCEDURE.



#### **TEMPERATURE PROFIL**





#### TECHNICAL DATA SHEET

#### **RIGHT ANGLE H2.6 RECEPTACLE SMT TYPE**

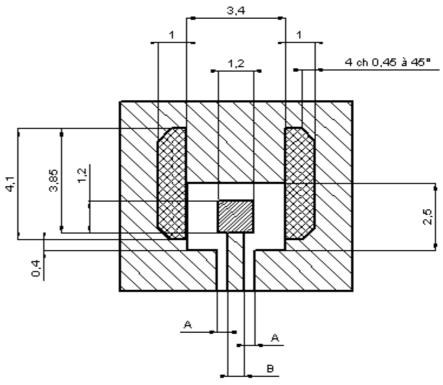
#### **REEL 700**

R107.103.020 Series : UMP

# **UMP SERIES INFORMATION**

### **PCB**

**COPLANAR LINE** Ground and signal are on the same side The material of PCB is glass is glass-epoxy Composite.





Gold over nickel for solder paste

Gold over nickel contact area free of any surface contaminant *1111111* 

Ground + varnish  $\Box \Box$ 

## **APPLICATION 75Ω**

**APPILCATION 50Ω** 

WITH $B = 0,55$ mm		WITH $B = 1,2mm$		
PCB thickness (mm)	Coplanar ligne A (mm)	PCB thickness (mm)	Coplanar ligne A (mm)	
0,8	0,57	0,8	0,183	
1,0	0,45	1,0	0,190	
1,2	0,41	1,2	0,195	
1,6	0,37	1,6	0,20	



